APPLI-TEC
THERMOSET ADHESIVE SOLUTIONS
ISO 9001 / AS9100 CERTIFIED

5302 Epoxy

1.85 W/mK

Appli-Tec 5302 epoxy was designed specifically for potting circuit board connectors. With its 4-hour pot life, the material is ideal for automated dispensing and features controlled flow – making it easy to deposit. 5302 meets NASA's outgassing requirements and has a wide range of curing options. The material bonds well with most substrates.

This product will exotherm if cured at high temperatures in masses greater than 5 grams. Contact Appli-Tec for step cure instructions if curing in larger masses.

UNCURED	
Pot Life @ 25°C	4 hours
Viscosity @ 25°C	125,000 cPs
Shelf Life @ -40°C	12 Months
Color	Blue
Thixotropic Index	1.9
CURE OPTIONS	1 hour @ 120°C 5 minutes @ 150°C
CURED PROPERTIES	Based on cure of 1 hour @ 120°C
Color	Dark Tan
Shore D Hardness	97
Glass Transition Temp. (°C)	134
Density (g/cc)	2.62
Lap Shear 2024T3 Clad (psi)	2,500
ELECTRICAL PROPERTIES	
Volume Resistivity (ohm-cm)	2.13E 16 @500 VDC
THERMAL PROPERTIES	Based on cure of 1 hour @ 120°C
Glass Transition Temp. (°C)	134
Thermal Conductivity (W/mK)	1.85
Degradation Temp. (°C)	275
OUTGASSING PROPERTIES	Based on cure of 1 hour @ 120°C
TML (%)	0.07
CVCM (%)	<0.01
WVR (%)	0.04
ACOUSTIC PROPERTIES	
Velocity (m/s)	3,450
Impedance (MRayles)	9.03
Loss (dB/cm-MHz)	-8.3
Density (g/cc)	2.62

KEY FEATURES

- High Thermal Conductivity
- Resistant to Fuel, Lubricants, Water, and Weather
- Bonds Well to Most Substrates
- Changes Color When Cured
- Snap Cure at 150 °C
- High Glass Transition Temperature
- High Temperature Resistant
- Long Pot Life
- Meets NASA Outgassing Requirements
- User-friendly Packaging

Talk to an engineer:

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